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Jameco Part Number 45794FSC

MM74HC32

Quad 2-Input OR Gate

General Description

The MM74HC32 OR gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs providing high noise immunity and the ability to drive 10 LS-TTL loads. The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family.

All inputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

Features

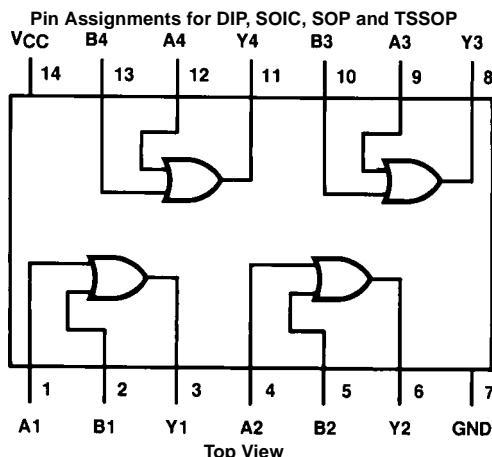
- Typical propagation delay: 10 ns
- Wide power supply range: 2–6V
- Low quiescent current: 20 μ A maximum (74HC Series)
- Low input current: 1 μ A maximum
- Fanout of 10 LS-TTL loads

Ordering Code:

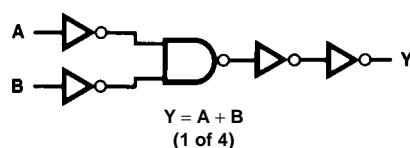
Order Number	Package Number	Package Description
MM74HC32M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow
MM74HC32SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC32MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC32N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Connection Diagram



Logic Diagram



Absolute Maximum Ratings^(Note 1) **Recommended Operating Conditions**

(Note 2)

			Min	Max	Units
Supply Voltage (V_{CC})	-0.5 to + 7.0V	Supply Voltage (V_{CC})	2	6	V
DC Input Voltage (V_{IN})	-1.5 to $V_{CC} + 1.5V$	DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
DC Output Voltage (V_{OUT})	-0.5 to $V_{CC} + 0.5V$	Operating Temperature Range (T_A)	-40	+85	°C
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA	Input Rise or Fall Times (t_r, t_f)	$V_{CC} = 2.0V$	1000	ns
DC Output Current, per pin (I_{OUT})	±25 mA	$V_{CC} = 4.5V$	500	ns	
DC V_{CC} or GND Current, per pin (I_{CC})	±50 mA	$V_{CC} = 6.0V$	400	ns	
Storage Temperature Range (T_{STG})	-65°C to +150°C				
Power Dissipation (P_D) (Note 3)	600 mW				
S.O. Package only	500 mW				
Lead Temperature (T_L) (Soldering 10 seconds)	260°C				

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics ^(Note 4)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^\circ C$		Guaranteed Limits	Units
				Typ			
V_{IH}	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	V
			4.5V		3.15	3.15	V
			6.0V		4.2	4.2	V
V_{IL}	Maximum LOW Level Input Voltage		2.0V		0.5	0.5	V
			4.5V		1.35	1.35	V
			6.0V		1.8	1.8	V
V_{OH}	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 20 \mu A$	2.0V	2.0	1.9	1.9	V
			4.5V	4.5	4.4	4.4	V
			6.0V	6.0	5.9	5.9	V
		$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 4.0 \text{ mA}$ $ I_{OUT} \leq 5.2 \text{ mA}$	4.5V	4.7	3.98	3.84	V
			6.0V	5.2	5.48	5.34	V
V_{OL}	Maximum LOW Level Output Voltage	$V_{IN} = V_{IL}$ $ I_{OUT} \leq 20 \mu A$	2.0V	0	0.1	0.1	V
			4.5V	0	0.1	0.1	V
			6.0V	0	0.1	0.1	V
		$V_{IN} = V_{IL}$ $ I_{OUT} \leq 4.0 \text{ mA}$ $ I_{OUT} \leq 5.2 \text{ mA}$	4.5V	0.2	0.26	0.33	V
			6.0V	0.2	0.26	0.33	V
I_{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	µA
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		2.0	20	µA

Note 4: For a power supply of $5V \pm 10\%$ the worst case output voltages (V_{OH} and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

$V_{CC} = 5V$, $T_A = 25^{\circ}C$, $C_L = 15 \text{ pF}$, $t_r = t_f = 6 \text{ ns}$

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL}, t_{PLH}	Maximum Propagation Delay		10	18	ns

AC Electrical Characteristics

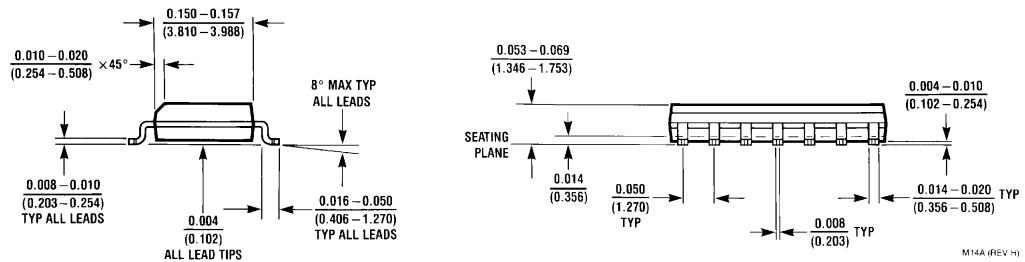
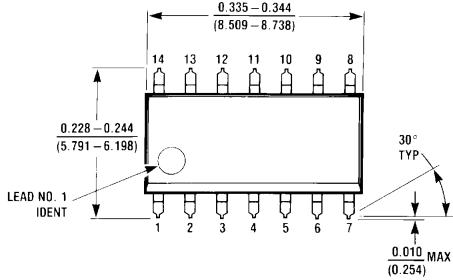
$V_{CC} = 2.0V$ to $6.0V$, $C_L = 50 \text{ pF}$, $t_r = t_f = 6 \text{ ns}$ (unless otherwise specified)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^{\circ}C$		Units
				Typ	Guaranteed Limits	
t_{PHL}, t_{PLH}	Maximum Propagation Delay		2.0V	30	100	ns
			4.5V	12	20	ns
			6.0V	9	17	ns
t_{TLH}, t_{THL}	Maximum Output Rise and Fall Time		2.0V	30	75	ns
			4.5V	8	15	ns
			6.0V	7	13	ns
C_{PD}	Power Dissipation Capacitance (Note 5)	(per gate)		50		pF
C_{IN}	Maximum Input Capacitance			5	10	10

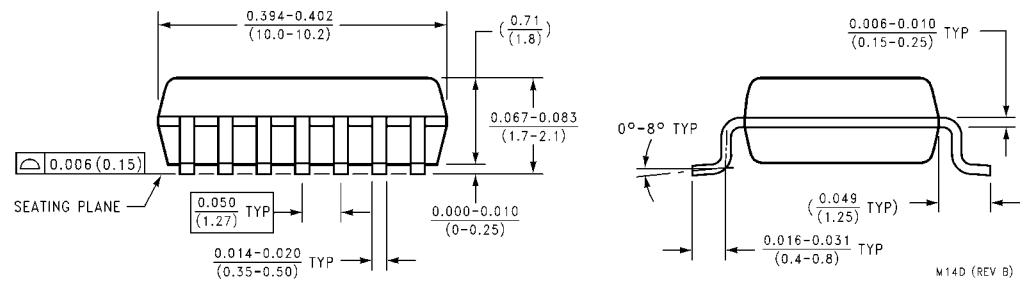
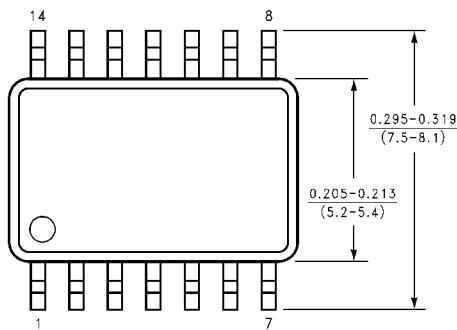
Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

Physical Dimensions

inches (millimeters) unless otherwise noted



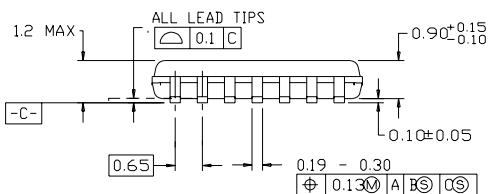
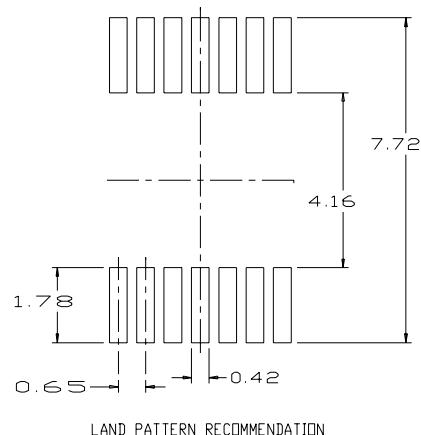
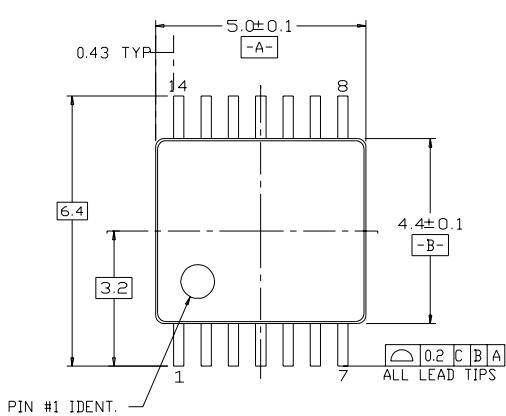
14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow
Package Number M14A



14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D

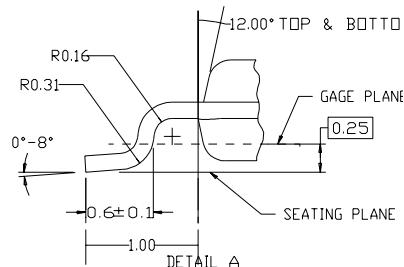
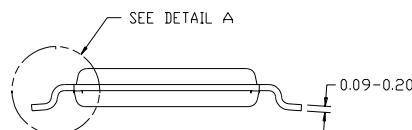
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

14LD, TSSOP, JEDEC MO-153, 4.4MM WIDE



NOTES:

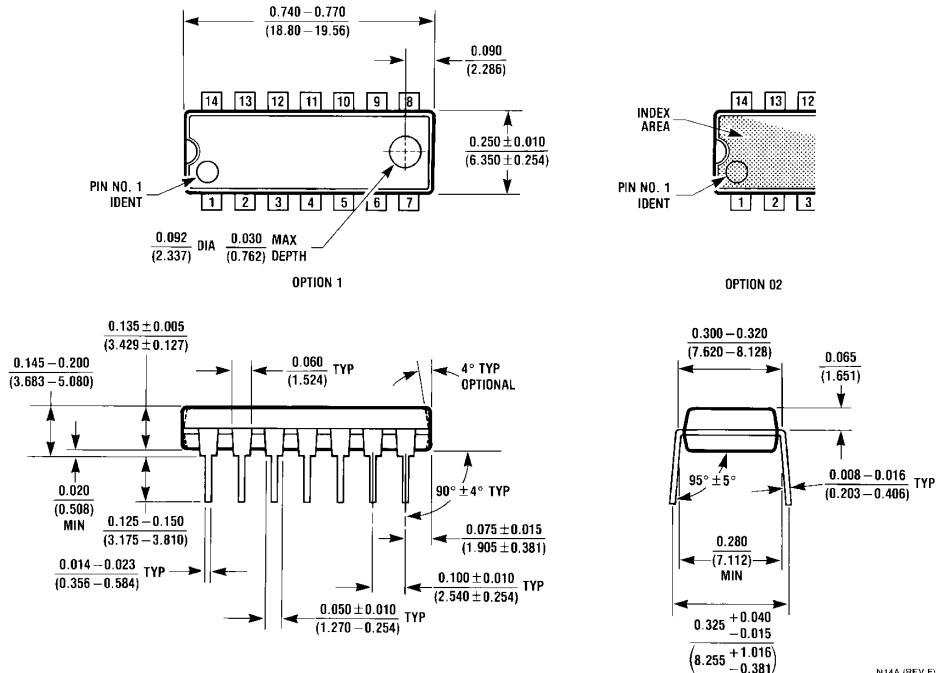
- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATED 7/93
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS



14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC14

Physical Dimensions

inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N14A

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